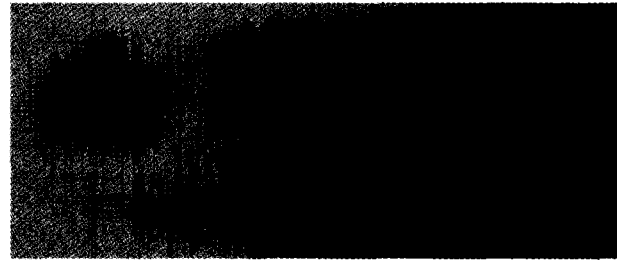
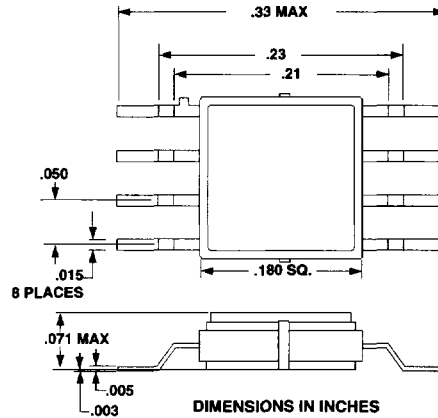
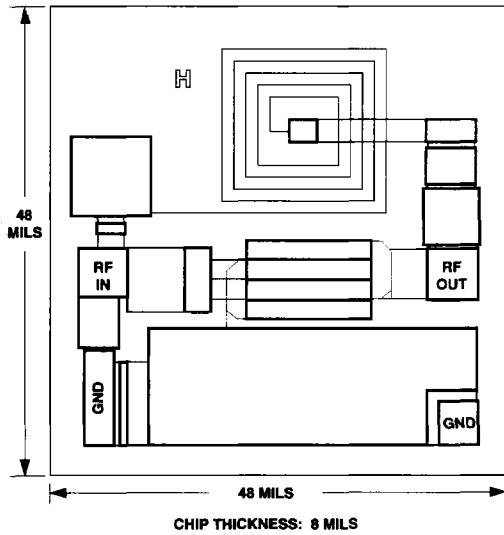


FEATURES

- 0.5 - 3.5 GHz Frequency Range
- Self Biased. No Separate Gate Supply Req.
- +20 dBm Output Power Capability
- Matched to 50 Ω



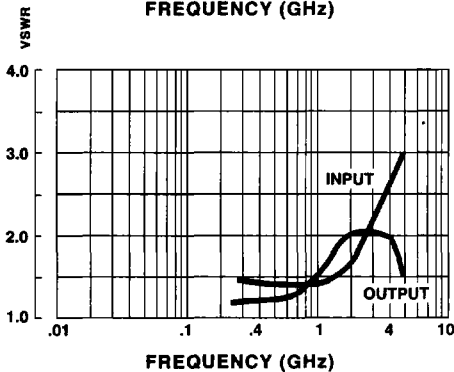
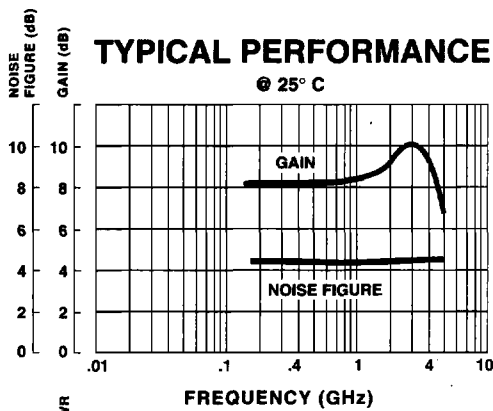
BOND PAD CONFIGURATION



PIN	FUNCTION
1	GND
2	GND
3	RF IN
4	GND
5	GND
6	GND
7	RF OUT
8	GND

.xx = .02
.xxx = .010

MMIC



GUARANTEED PERFORMANCE

@ 25° C

PARAMETER	MIN	TYP	MAX	UNITS	CONDITIONS
OPERATING FREQUENCY	0.5		3.5	GHz	
GAIN		8.7 9.0		dB dB	0.5 - 2.0 GHz 0.5 - 3.5 GHz
GAIN FLATNESS		±0.2 ±0.75		dB dB	0.5 - 2.0 GHz 0.5 - 3.5 GHz
VSWR:					
INPUT		1.7/1 2.5/1	3.0/1		0.5 - 2.0 GHz 0.5 - 3.5 GHz
OUTPUT		1.7/1 2.5/1	2.2/1 3.0/1		0.5 - 2.0 GHz 0.5 - 3.5 GHz
OUTPUT POWER	+18	+20		dBm	1 dB COMPRESSION
NOISE FIGURE		4.5		dB	
VOLTAGES:	DRAIN	+4.5	+5.0	+6.0	V
CURRENT DRAIN		90		mA	

CONDITION IS Vd = 5 VOLTS, Id = 90 mA

NOTES:

1. THE VALUE OF Id = 90 mA IS TYPICAL WHEN Vd = 5 VOLT.
2. IT IS IMPORTANT THAT THE PADS DESIGNATED GROUND ARE BONDED WITH MINIMUM INDUCTANCE TO A GOOD RF GROUND.
3. EXTERNAL BIAS CIRCUITRY IS REQUIRED AT RF OUT AND A DC BLOCKING CAPACITOR AT RF IN.
4. FOLLOW RECOMMENDED MOUNTING INSTRUCTIONS.
5. ORDER: P35-4101-0 FOR CHIP CONFIGURATION, P35-4101-2 FOR PACKAGE.